Developments in Printable Organic Transistors

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About the author

Dr Kahn is a consultant specialising in the multidisciplinary fields of printable electronics, radio frequency identification (RFID), and smart packaging. Previously, he was a Professor at Rochester Institute of Technology, where he started the printable electronics research programme. Dr Kahn has been involved in investigations, assessment, and development of the use of printing techniques (particularly high-volume printing processes) and materials for the fabrication of electronic devices. His work (both small and production scale) has produced and characterised antennas for RFID tags. He has assessed the process capabilities of a number of different printing techniques that have been used for patterning conductive features. Dr Kahn has developed and applied technology that can be used for printing chemical sensors. He has also worked on printing RFID antennas directly onto corrugated cardboard substrates, and investigated the effects of environment and conditioning on electrical conductivity. Dr Kahn is currently investigating other techniques for patterning functional organic materials, such as liquid dispensing, and has created working organic transistors using this technique.

Dr Kahn has a Ph.D. in Chemistry from the University of Nebraska, and an S. B. in Chemistry from the University of Chicago. He is the author of over 75 publications. Dr Kahn is well known in the fields of printed electronics, RFID, and smart packaging, and speaks regularly and teaches master classes in the US and abroad.

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